

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

"- TTD MAN					
	Symbol	Value	Unit		
Rever <mark>se Voltage</mark>	V _R	75	V		
Peak Reverse Voltage	V _{RM}	100	V		
Rectified Current (Average) Half Wave Rectification with Resist. Load at $T_{amb} = 25$ °C and $\ge f \ge 50$ Hz	IO	150 ¹⁾	mA		
Surge Forward Current at t < 1 s and $T_j = 25 \degree C$	I _{FSM}	500	mA		
Power Dissipation at T _{amb} = 25 °C	P _{tot}	350 ¹⁾	mW		
Junction Temperature	Tj	150	°C		
Stora <mark>ge Temp</mark> erature Range	Ts	-65 to +150	°C		
¹⁾ Device on fiberglass substrate, see layout			1		



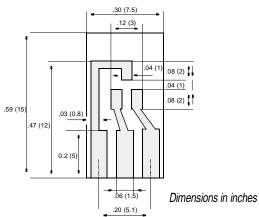


IMBD4148

ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit
Forward Voltage at I _F = 10 mA	VF	-	-	1	V
Leakage Current at $V_R = 70 V$ at $V_R = 70 V$, $T_j = 150 °C$ at $V_R = 25 V$, $T_j = 150 °C$	I _R I _R I _R			2.5 50 30	μΑ μΑ μΑ
Capacitance at $V_F = V_R = 0$	C _{tot}	-	-	4	pF
Reverse Recovery Time from I_F = 10 mA to I_R = 10 mA V_R = 6 V, R_L = 100 Ω	t _{rr}	-	-	4	ns
Thermal Resistance Junction to Ambient Air	R _{thJA}	-	-	450 ¹⁾	K/W



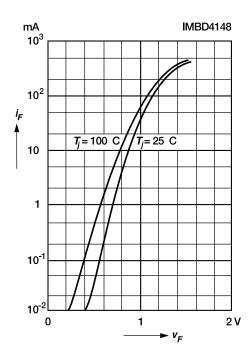
Dimensions in inches (millimeters)

Layout for R_{thJA} test Thickness: Fiberglass 0.059 in (1.5 mm) Copper leads 0.012 in (0.3 mm)

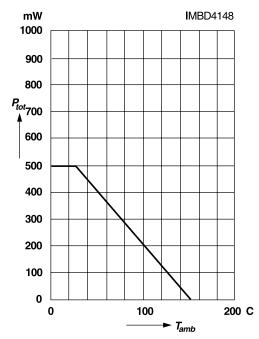
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RATINGS AND CHARACTERISTIC CURVES IMBD4148

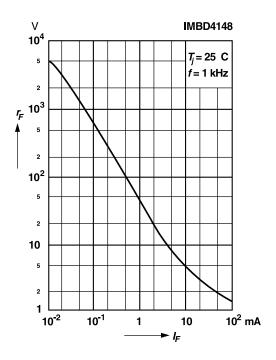
Forward characteristics



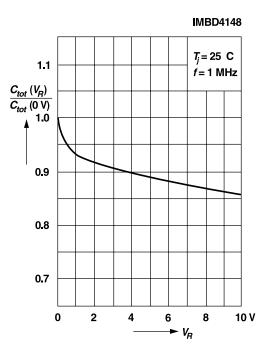




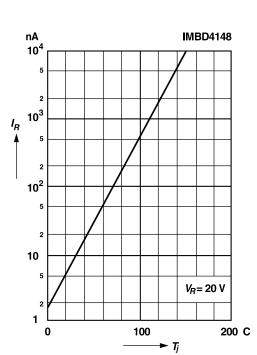
Dynamic forward resistance versus forward current



Relative capacitance versus reverse voltage

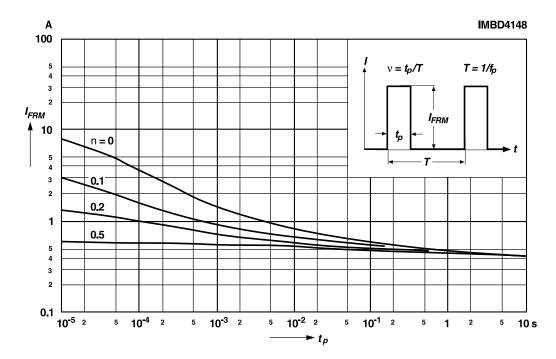


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Leakage current versus junction temperature

Admissible repetitive peak forward current versus pulse duration For conditions, see footnote in table "Absolute Maximum Ratings"



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